

40V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	I_D $T_A = 25^\circ C$
40V	34mΩ @ $V_{GS} = 10V$	7.2A
	59mΩ @ $V_{GS} = 4.5V$	5.5A

Features and Benefits

- 100% Unclamped Inductive Switch (UIS) test in production
- Low on-resistance
- Fast switching speed
- Max Q_g rated
- "Green" component and RoHS compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

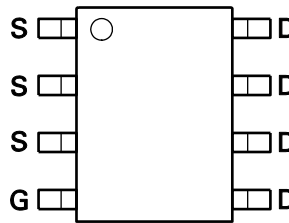
- Motor control
- Backlighting
- DC-DC Converters
- Power management functions

Mechanical Data

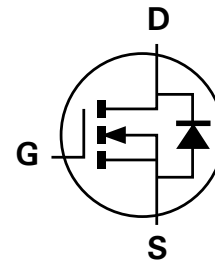
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Weight: 0.074 grams (approximate)



Top View



Top View



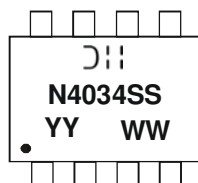
Equivalent Circuit

Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN4034SSS-13	N4034SS	13	12	2,500

Note: 1. Diodes, Inc. defines "Green" products as those which are RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.

Marking Information



DII = Manufacturer's Marking
 N4034SS = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Year (ex: 09 = 2009)
 WW = Week (01 - 53)

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

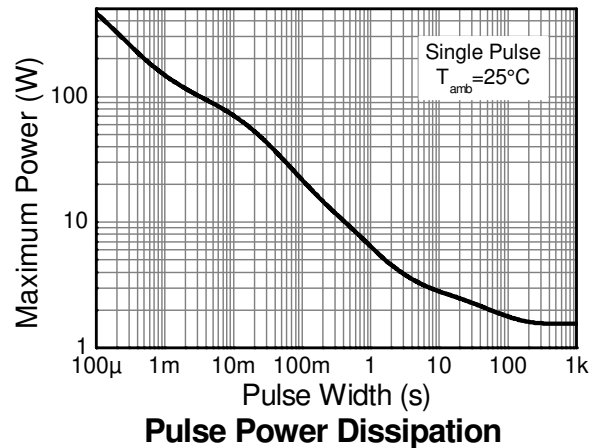
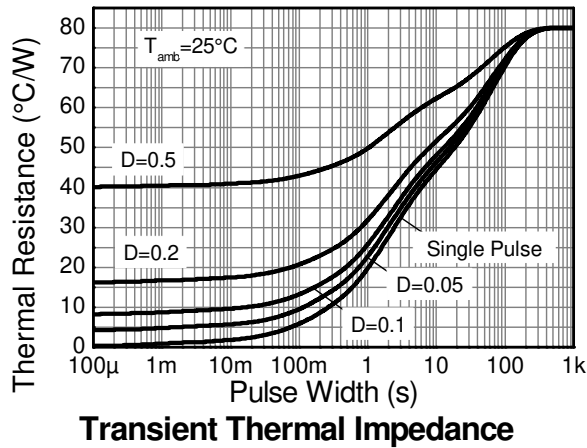
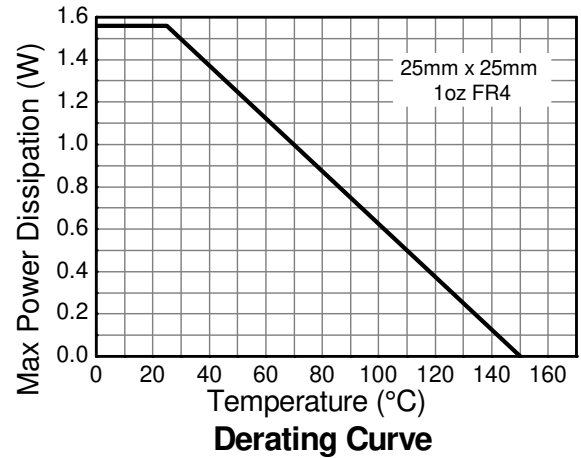
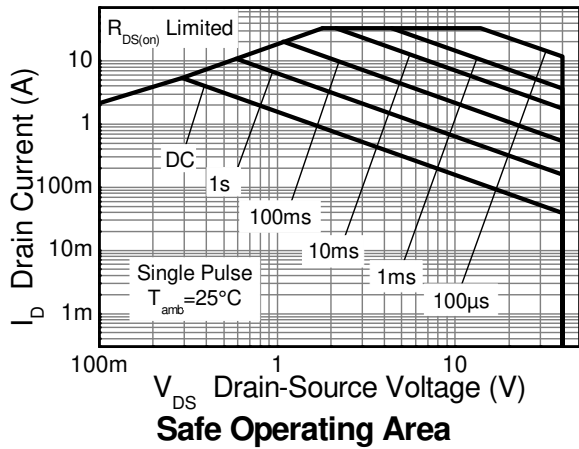
Characteristic			Symbol	Value	Unit	
Drain-Source voltage			V_{DSS}	40	V	
Gate-Source voltage		(Note 2)	V_{GS}	± 20	V	
Single Pulsed Avalanche Energy		(Note 7)	E_{AS}	27	mJ	
Single Pulsed Avalanche Current		(Note 7)	I_{AS}	15.25	A	
Continuous Drain current	$V_{GS} = 10\text{V}$	(Note 4)	I_D	7.2	A	
		$T_A = 70^\circ\text{C}$ (Note 4)		5.8		
		(Note 3)		5.4		
Pulsed Drain current	$V_{GS} = 10\text{V}$	(Note 5)	I_{DM}	33.0	A	
Continuous Source current (Body diode)			(Note 4)	I_S	4.1	A
Pulsed Source current (Body diode)			(Note 5)	I_{SM}	33.0	A

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic		Symbol	Value	Unit
Power dissipation	(Note 3)	P_D	1.56	W
Linear derating factor	(Note 4)		12.5	
			2.8	
Thermal Resistance, Junction to Ambient	(Note 3)	$R_{\theta JA}$	80	$^\circ\text{C/W}$
	(Note 4)		44.5	
Thermal Resistance, Junction to Lead	(Note 6)	$R_{\theta JL}$	37	$^\circ\text{C/W}$
Operating and storage temperature range		T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

- Notes:
- AEC-Q101 V_{GS} maximum is $\pm 16\text{V}$.
 - For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 - Same as note (3), except the device is measured at $t \leq 10$ sec.
 - Same as note (3), except the device is pulsed with $D = 0.02$ and pulse width 300 μs . The pulse current is limited by the maximum junction temperature.
 - Thermal resistance from junction to solder-point (at the end of the drain lead).
 - UIS in production with $L = 100\mu\text{H}$, $V_{DD} = 40\text{V}$.

Thermal Characteristics

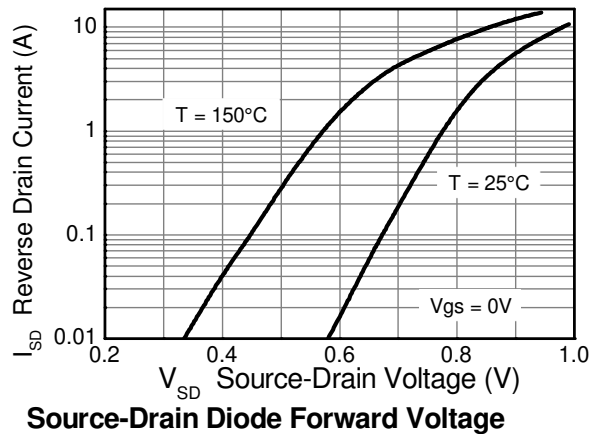
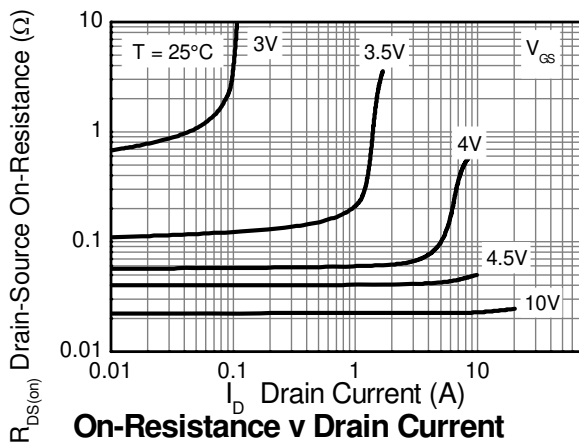
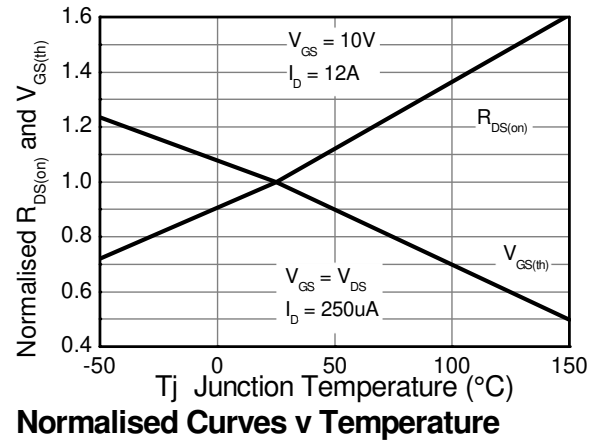
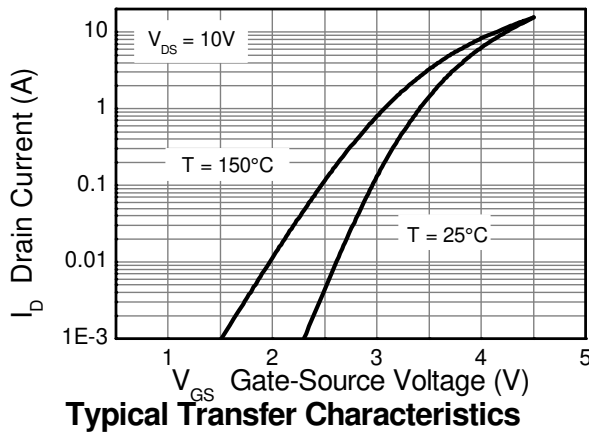
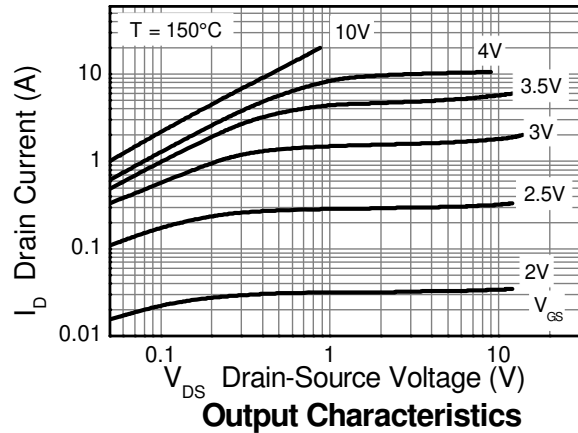
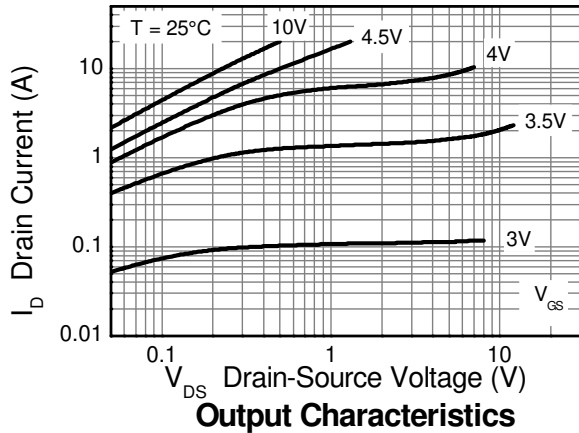


Electrical Characteristics @T_A = 25°C unless otherwise specified

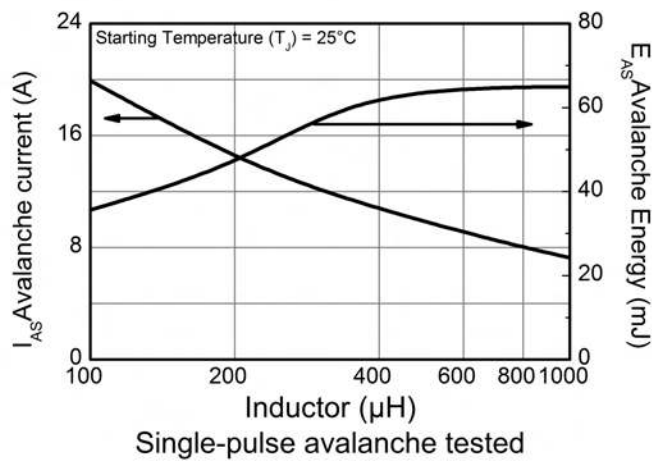
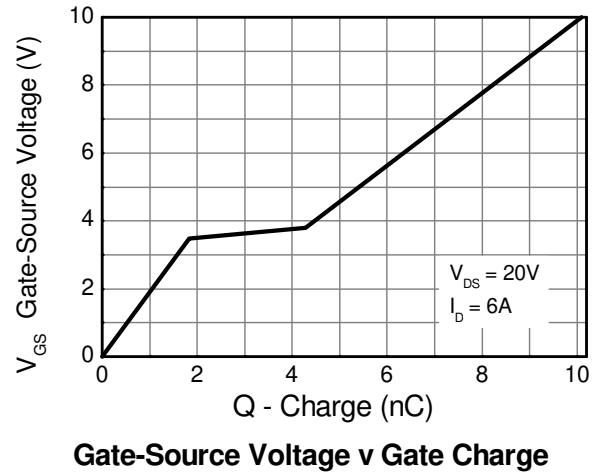
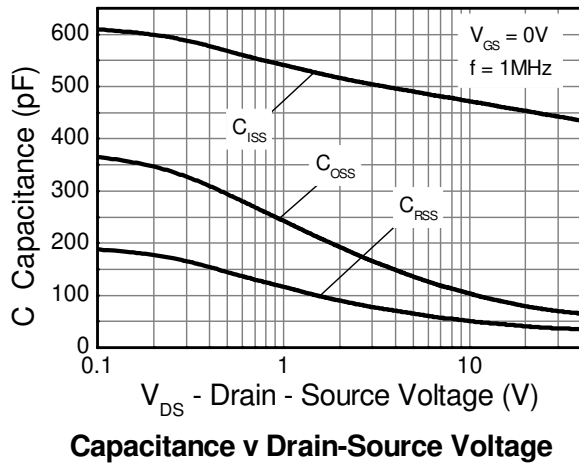
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	40	—	—	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 40V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	1.0	—	3.0	V	I _D = 250μA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance (Note 8)	R _{DS(on)}	—	0.023	0.034	Ω	V _{GS} = 10V, I _D = 6A
			0.039	0.059		V _{GS} = 4.5V, I _D = 5A
Forward Transconductance (Notes 8 & 9)	g _{fs}	—	20.5	—	S	V _{DS} = 15V, I _D = 6A
Diode Forward Voltage (Note 8)	V _{SD}	—	0.87	1.1	V	I _S = 6A, V _{GS} = 0V
Reverse recovery time (Note 9)	t _{rr}	—	11.9	—	ns	I _S = 2.5A, di/dt = 100A/μs
Reverse recovery charge (Note 9)	Q _{rr}	—	4.9	—	nC	
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	—	453	—	pF	V _{DS} = 20V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{oss}	—	79.1	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	40.5	—	pF	
Total Gate Charge (Note 10)	Q _g	—	4.9	8	nC	V _{GS} = 4.5V
Total Gate Charge (Note 10)	Q _g	—	10	18	nC	V _{GS} = 10V
Gate-Source Charge (Note 10)	Q _{gs}	—	1.8	—	nC	
Gate-Drain Charge (Note 10)	Q _{gd}	—	2.4	—	nC	
Turn-On Delay Time (Note 10)	t _{D(on)}	—	2.7	—	ns	V _{DD} = 20V, V _{GS} = 10V I _D = 1A, R _G ≅ 6.0Ω
Turn-On Rise Time (Note 10)	t _r	—	2.7	—	ns	
Turn-Off Delay Time (Note 10)	t _{D(off)}	—	14	—	ns	
Turn-Off Fall Time (Note 10)	t _f	—	6	—	ns	

- Notes:
- 8. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%
 - 9. For design aid only, not subject to production testing.
 - 10. Switching characteristics are independent of operating junction temperatures.

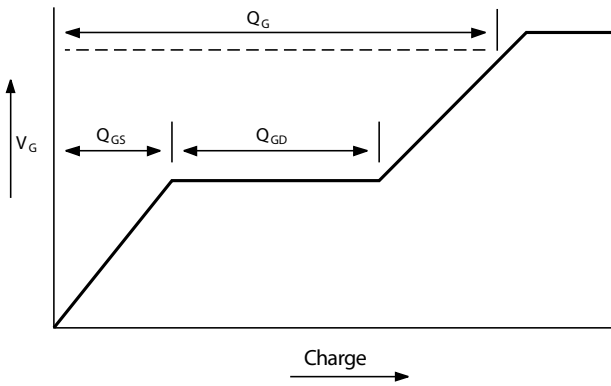
Typical Characteristics



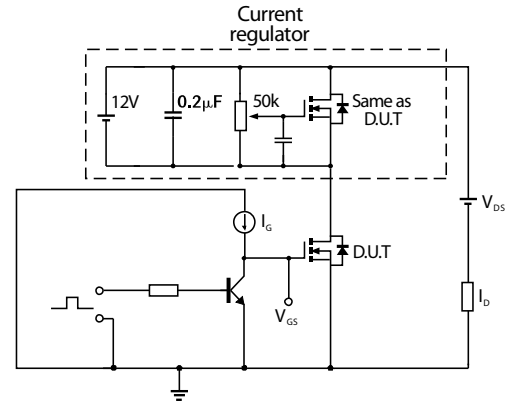
Typical Characteristics – continued



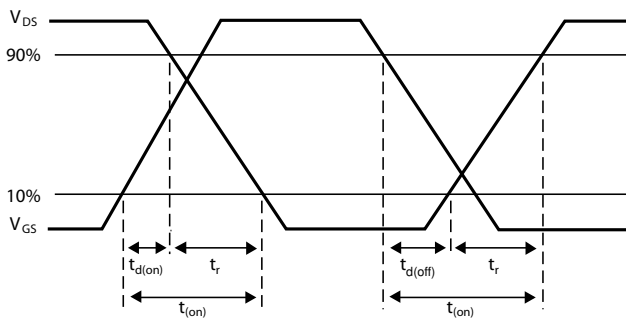
Test Circuits



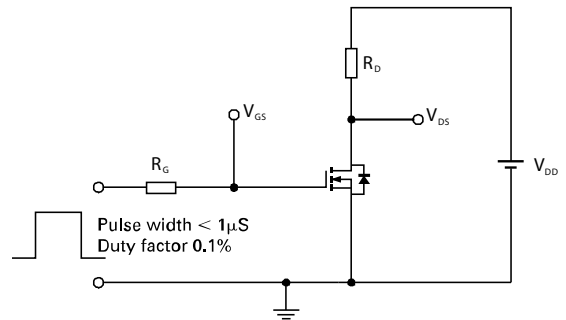
Basic gate charge waveform



Gate charge test circuit

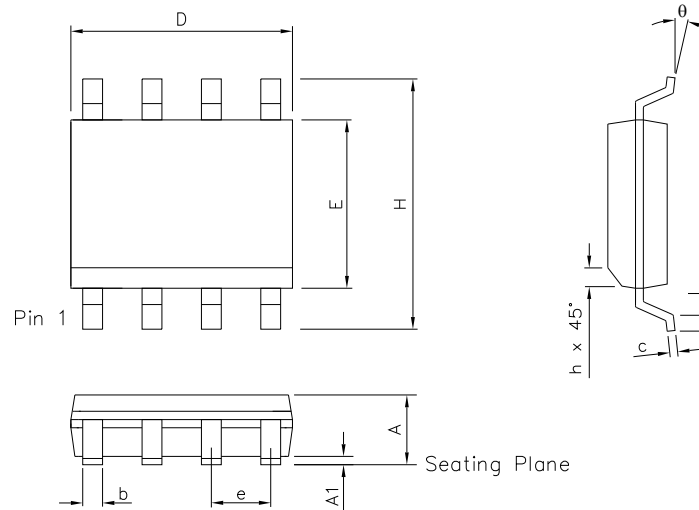


Switching time waveforms



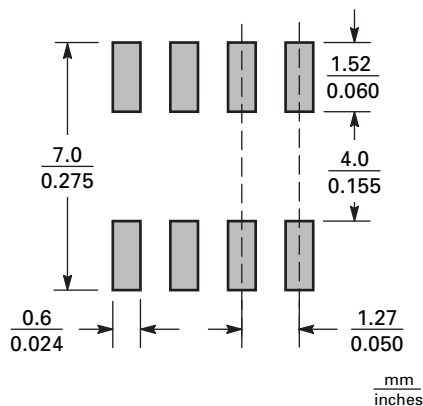
Switching time test circuit

Package Outline Dimensions



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.053	0.069	1.35	1.75	e	0.050 BSC		1.27 BSC	
A1	0.004	0.010	0.10	0.25	b	0.013	0.020	0.33	0.51
D	0.189	0.197	4.80	5.00	c	0.008	0.010	0.19	0.25
H	0.228	0.244	5.80	6.20	theta	0°	8°	0°	8°
E	0.150	0.157	3.80	4.00	h	0.010	0.020	0.25	0.50
L	0.016	0.050	0.40	1.27	-	-	-	-	-

Suggested Pad Layout



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